



***'Future Automotive Electronics - providing European high reliability solutions'***



**Date: January 21 & 22, 2016**

**Location: Hotel Pullman Dresden Newa  
Dresden, Germany**



**Bonus programme: Factory visit at Volkswagen Phaeton - 'Die Gläserne Manufaktur'**

*Please note: numbers of visitors at Volkswagen are limited, on a first-come, first-served basis, so make sure you are one of the first.*

**Day 1: 08:30-22:00 hrs.**

- **Welcome and Market Overview by Alun Morgan, Chairman EIPC**
- **Session 1: Management - “New ways to strengthen the PCB industry in Europe”**
- **Session 2: What is new in PCB conductors and solder mask Imaging**
- **Networking Lunch**
- **Bonus programme: Visit Volkswagen Phaeton Factory**
- **Networking dinner Dresden**



**Day 2: 09:00-14:50 hrs.**

- **Session 3: OEM needs and PCB fabricators' solutions Making quality measurable**
- **Session 4: Future technology requirements for chip packaging and device embedding in PCBs**
- **Networking Lunch**
- **Session 5: Design Know-How for manufacturing. How to meet industry needs for training and standardisation**



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# EIPC Winter Conference Dresden, Germany, January 21 & 22, 2016

*"Future Automotive Electronics - providing European high reliability solutions"*

## Programme

The European Institute of Printed Circuits (EIPC) is extending an invitation to companies and individuals active in the Packaging and Interconnection Industry to participate in the EIPC Winter Conference to be held on January 21 & 22, 2016 in Dresden, Germany. The aim of the Conference is to provide a platform for speakers and delegates to exchange information on market conditions and future innovation on interconnection and packaging.

Delegates and visitors from throughout Europe will attend this event, offering presenters the opportunity to reach a targeted audience of decision makers and leaders of the international packaging and interconnection industry. This conference is an absolute 'must' for companies associated with PCB fabrication who wish to stay up to date with the latest market requirements, materials, fabrication equipment and manufacturing processes who also need to improve the efficiency of their processes and the reliability of their products.

## Who should attend?

Engineers and decision-makers in the field of OEMs, EMS, assembly, and PCB fabricators as well as board and system designers at all levels are invited to participate. Circuit board designers, looking into more cost-effective solutions and miniaturisation, will learn about the developing trends in different applications. Board fabricators and development engineers will gain background information that will help to focus on more profitable products. Specialists and marketing managers will gain additional background data to focus on advanced PCB applications. OEMs will get a better understanding on how to get prepared for the next generation of electronic products.

## Detailed information about the conference hotel

EIPC has chosen the **Pullman Dresden Newa** as conference location. The hotel is located in the city centre, right on the Prager Strasse shopping boulevard, near Dresden's renowned sights and major business addresses and 300m from the main station.

## Hotel Pullman Dresden Newa

Prager Strasse 2a  
01069 Dresden, Germany  
Tel: +49-351 4814 109  
info@pullman-dresden.com  
www.pullmanhotels.com

EIPC has negotiated a special rate for a single room of **EURO 99** per night including breakfast. For reservations please contact the hotel direct by phone or by email. Please use the code "EIPC". The reservation deadline is January 6, 2016. After this release date availability is on request.

## Bonus Programme

On January 21, we will visit the Volkswagen Phaeton factory 'Die Gläserne Manufaktur'. We will go by coach from the conference hotel. Please mark separately on your form if you wish to participate in the company visit.

## Networking Event

On Thursday evening, after the tour at Volkswagen, we will be having dinner all together in Dresden. An opportunity to chat, gossip, enjoy good food and wine, and maybe learn something one didn't know. As usual, this will be a convivial and sociable event open to conference delegates and their guests.

## Table top exhibition and poster display area

During the Conference the EIPC will provide an opportunity for information sharing and discussion in a dedicated area. This will allow visitors to obtain latest product information and know how on an informal, or 'one-to-one' basis. A 'poster wall' and a table will be provided during the two days of the conference. If you are interested please download the registration form at [www.eipc.org](http://www.eipc.org).

## Conference Sponsoring

The EIPC offers several possibilities for sponsoring the EIPC Winter Conference Dresden 2016. You can download the various possibilities that could be a great asset to your company's exposure on the EIPC website.

## Sponsors of the EIPC Winter Conference Dresden:

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# Conference Programme Day 1, Thursday January 21

08:15-08:30	Conference Registration and Table Top & Poster Exhibition build up	Table Top & Poster Display Area
08:30-08:45	Welcome and Market Overview by the EIPC Chairman	Alun Morgan, EIPC, UK
<b>Session 1: Management "New ways to strengthen the PCB industry in Europe"</b>		<b>Moderator: Alun Morgan, EIPC, UK</b>
08:45-09:15	Business Outlook Global Electronics Industry	Walt Custer, Custer Consulting, USA
09:15-09:35	Business Model, quality & cost effectiveness for the automotive industry	Slim Sellami, Fuba Printed Circuits Tunisie, TN
09:35-09:55	Romania a local alternative to Asia for manufacturing	Steve Driver, Spirit Circuits, UK
09:55-10:15	Inkjet, changing the rules for more efficient PCB manufacturing	Henk Jan Zwiers, Mutracx, NL
10:15-10:30	Panel discussion	
10:30-11:00	30 minutes Coffee break	Table Top & Poster Display Area
<b>Session 2: What is new in PCB conductors and solder mask Imaging</b>		<b>Moderator: Oldrich Simek, PragoBoard s.r.o., CZ</b>
11:00-11:20	How Direct Imaging Technology using modern UV and near UV LED technology solves the complete Spectrum of Exposure Problems	Paul Waldner, mie, DE (on behalf of MIVA Technologies)
11:20-11:40	Direct Imaging Solution for Solder Mask	Uwe Altmann, Orbotech, BE
11:40-12:00	Best in class LDI-Technology for dry film and solder mask from a German High-Tech manufacturing	Attila Heim, Limata GmbH, DE
12:00-12:20	White soldermask for LEDs, not your typical mask	Don Monn, Taiyo America, USA
12:20-12:30	Panel discussion	
12:30-13:30	Networking Lunch	Hotel Restaurant
13:30	Departure from Hotel for Tour Volkswagen "Die Gläserne Manufaktur" Group 1	
14:00-15:45	Tour Volkswagen "Die Gläserne Manufaktur"	
15:30	Departure from Hotel for Tour Volkswagen "Die Gläserne Manufaktur" Group 2	
16:00-17:45	Tour Volkswagen "Die Gläserne Manufaktur"	
19:00	Departure Networking Dinner Dresden from Hotel	
22:00	Return to Hotel	

*The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters.  
Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.*



## Conference Programme Day 2, Friday January 22

<b>Session 3: OEM needs and PCB fabricators' solutions Making quality measurable</b>		<b>Moderator: Alun Morgan, EIPC, UK</b>
09:00-09:10	Welcome day 2 and Introduction	Alun Morgan, EIPC, UK
09:10-09:50	New test strategies. Creating Industry based performance criteria for PWB substrates	Bill Birch, PWB Interconnect Solutions, CA
09:50-10:10	Compliance & Performance Testing and Meeting the OEM's Needs	Emma Hudson, UL, UK
10:10-10:30	Reliability of Multi-Lamination Structures in Pb-free Assembly	Bill Birch, HDPU, CA
10:30-10:40	Panel Discussion	
10:40-11:10	<b>30 minutes Coffee break</b>	<b>Table Top &amp; Poster Display Area</b>
<b>Session 4: Future technology requirements for chip packaging and device embedding in PCBs</b>		<b>Moderator: Paul Waldner, mie, DE</b>
11:10-11:30	Technical requirement for drilling/laser machines for embedded technology	Stephan Kunz, Schmoll Maschinen, DE
11:30-11:50	Material Requirements for 77GHz Automotive Radar Applications and Characterization of the Electrical Properties	Alexander Ippich, Isola, DE
11:50-12:10	Improving quality and efficiency of PCB electroplating – an innovative simulation-driven approach	Robrecht Belis, Elsyca, BE
12:10-12:20	Panel Discussion	
12:20-13:30	<b>Networking Lunch</b>	<b>Hotel Restaurant</b>
<b>Session 5: Design Know-How for manufacturing. How to meet industry needs for training and standardisation</b>		<b>Martyn Gaudion, Polar Instruments, UK</b>
13:30-14:10	Fundamental Considerations to EMC on Printed Circuit Boards	Prof. Thüringer, FED, DE
14:10-14:30	Failure of printed circuit board assemblies (PCBAs) – Field experience and counter measures	Jens H. Klingel, KC Produkte, DE
14:30-14:40	Panel discussion	
14:40-14:50	<b>Chairman closing remarks - End of conference day 2</b>	

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